

# STS1NK60Z

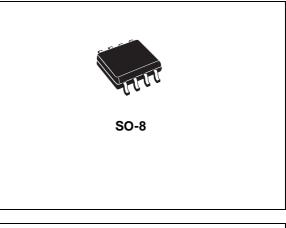
## N-CHANNEL 600V - 13Ω - 0.25A - SO-8 Zener-Protected SuperMESH<sup>™</sup> Power MOSFET

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	ID	Pw
STS1NK60Z	600 V	< 15 Ω	0.25 A	2 W

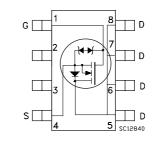
- TYPICAL  $R_{DS}(on) = 13\Omega$
- EXTREMELY HIGH dv/dt CAPABILITY
- ESD IMPROVED CAPABILITY
- 100% AVALANCHE TESTED
- NEW HIGH VOLTAGE BENCHMARK
- GATE CHARGE MINIMIZED

#### DESCRIPTION

The SuperMESH<sup>™</sup> series is obtained through an extreme optimization of ST's well established stripbased PowerMESH<sup>™</sup> layout. In addition to pushing on-resistance significantly down, special care is taken to ensure a very good dv/dt capability for the most demanding applications. Such series complements ST full range of high voltage MOSFETs including revolutionary MDmesh<sup>™</sup> products.







#### **APPLICATIONS**

- AC ADAPTORS AND BATTERY CHARGERS
- SWITH MODE POWER SUPPLIES (SMPS)

#### **ORDERING INFORMATION**

SALES TYPE	MARKING	PACKAGE	PACKAGING
STS1NK60Z	S1NK60Z	SO-8	TAPE & REEL

### STS1NK60Z

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	600	V
V <sub>DGR</sub>	Drain-gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	600	V
V <sub>GS</sub>	Gate- source Voltage	± 30	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>C</sub> = 25°C	0.25	А
ID	Drain Current (continuous) at T <sub>C</sub> = 100°C	0.16	А
I <sub>DM</sub> (•)	Drain Current (pulsed)	1	А
P <sub>TOT</sub>	Total Dissipation at $T_C = 25^{\circ}C$	2	W
	Derating Factor	0.016	W/°C
V <sub>ESD(G-S)</sub>	Gate source ESD(HBM-C=100pF, R=1.5KΩ)	800	V
dv/dt (1)	Peak Diode Recovery voltage slope	4.5	V/ns
T <sub>j</sub> T <sub>stg</sub>	Operating Junction Temperature Storage Temperature	-55 to 150 -55 to 150	0° 0°

(•) Pulse width limited by safe operating area

(1)  $I_{SD} \leq 0.3A$ , di/dt  $\leq 200A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_j \leq T_{JMAX}$ .

#### THERMAL DATA

Rthj-amb Thermal Resistance Junction-ambient Max	62.5	°C/W
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#### GATE-SOURCE ZENER DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
BV <sub>GSO</sub>	Gate-Source Breakdown Voltage	lgs=± 1mA (Open Drain)	30			V

#### PROTECTION FEATURES OF GATE-TO-SOURCE ZENER DIODES

The built-in back-to-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.

# **ELECTRICAL CHARACTERISTICS** (T<sub>CASE</sub> =25°C UNLESS OTHERWISE SPECIFIED) ON/OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	600			V
IDSS	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating, T <sub>C</sub> = 125 °C			1 50	μA μA
IGSS	Gate-body Leakage Current (V <sub>DS</sub> = 0)	$V_{GS} = \pm 20V$			±10	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 50 \ \mu A$	3	3.75	4.5	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.4 A		13	15	Ω

#### DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	V <sub>DS</sub> = V, I <sub>D</sub> = 0.4 A		0.5		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 25V, f = 1 MHz, V <sub>GS</sub> = 0		94 17.6 2.8		pF pF pF
C <sub>oss eq.</sub> (3)	Equivalent Output Capacitance	$V_{GS} = 0V$ , $V_{DS} = 0V$ to $480V$		11		pF

#### SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Delay Time Rise Time			5.5 5		ns ns
Q <sub>g</sub> Q <sub>gs</sub> Q <sub>gd</sub>	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 480$ V, $I_D = 0.8$ A, $V_{GS} = 10$ V		4.9 1 2.7	6.9	nC nC nC

#### SWITCHING OFF

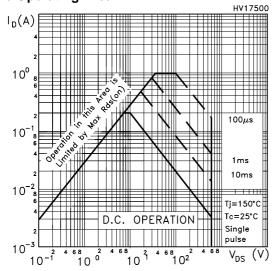
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(off)</sub> t <sub>f</sub>	Turn-off Delay Time Fall Time			13 28		ns ns
t <sub>r(Voff)</sub> t <sub>f</sub> t <sub>c</sub>	Off-voltage Rise Time Fall Time Cross-over Time	$\label{eq:VDD} \begin{array}{l} V_{DD} = 480 \text{V}, \ \text{I}_D = 0.8 \text{A}, \\ \text{R}_G = 4.7 \Omega, \ \text{V}_{GS} = 10 \text{V} \\ (\text{Inductive Load see, Figure 5}) \end{array}$		28 12.5 48		ns ns ns

#### SOURCE DRAIN DIODE

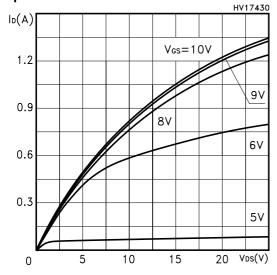
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (2)	Source-drain Current Source-drain Current (pulsed)				0.25 1	A A
V <sub>SD</sub> (1)	Forward On Voltage	$I_{SD} = 0.25A, V_{GS} = 0$			1.6	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 0.8 \text{ A}, \text{ di/dt} = 100 \text{A/} \mu \text{s}$ $V_{DD} = 20 \text{V}, \text{ T}_{\text{j}} = 150 ^{\circ} \text{C}$ (see test circuit, Figure 5)		140 224 3.2		ns nC A

Note: 1. Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
2. Pulse width limited by safe operating area.
3. C<sub>oss eq</sub> is defined as a constant equivalent capacitance giving the same charging time as C<sub>oss</sub> when V<sub>DS</sub> increases from 0 to 80% V<sub>DSS</sub>.

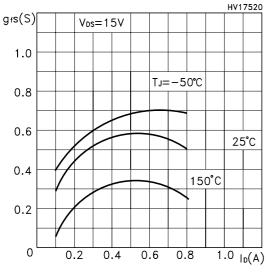
#### Safe Operating Area



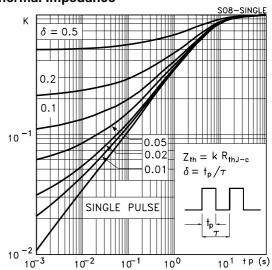
**Output Characteristics** 



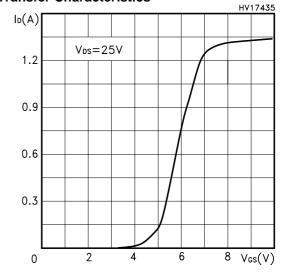
Transconductance



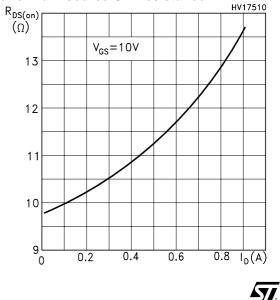




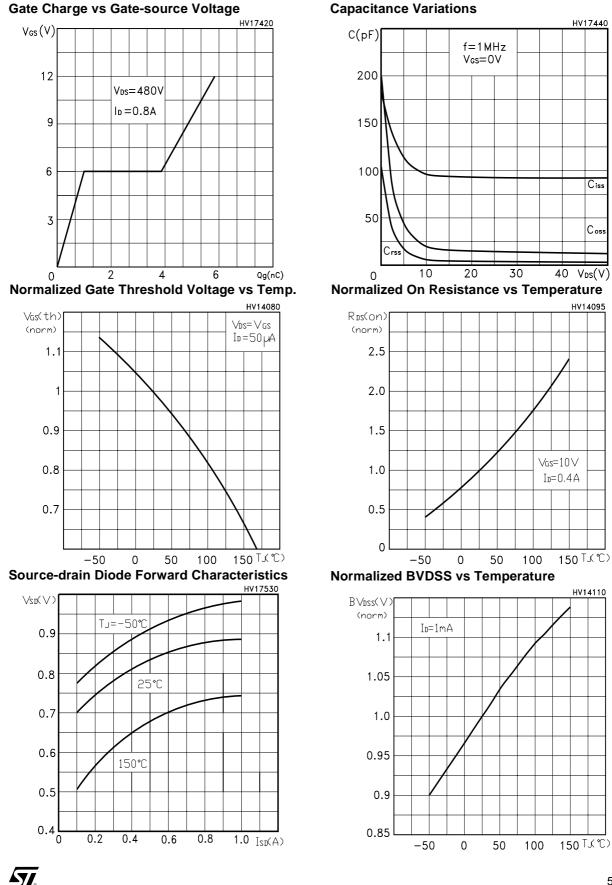
**Transfer Characteristics** 







4/8

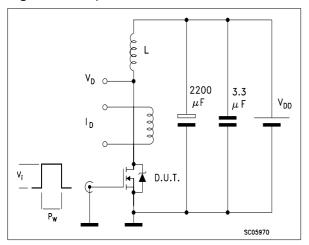


Gate Charge vs Gate-source Voltage

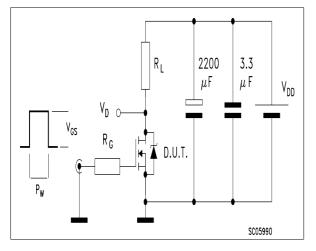
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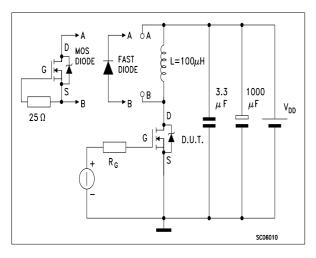
Fig. 1: Unclamped Inductive Load Test Circuit



**Fig. 3:** Switching Times Test Circuit For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



#### Fig. 2: Unclamped Inductive Waveform

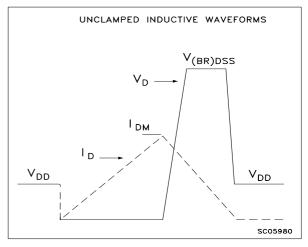
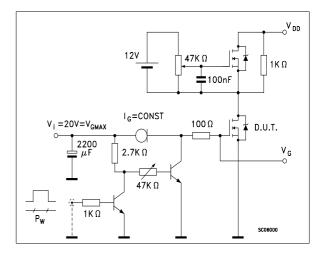


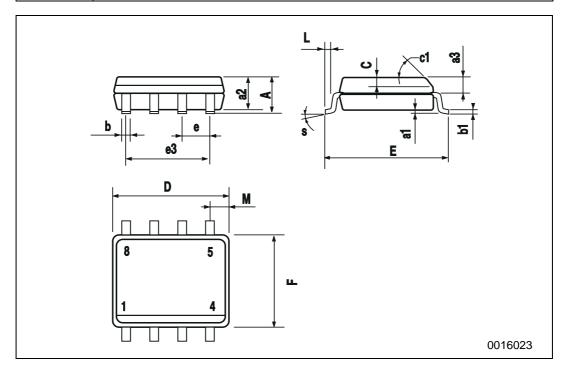
Fig. 4: Gate Charge test Circuit



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DIM.	mm			inch			
DIM.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А			1.75			0.068	
a1	0.1		0.25	0.003		0.009	
a2			1.65			0.064	
a3	0.65		0.85	0.025		0.033	
b	0.35		0.48	0.013		0.018	
b1	0.19		0.25	0.007		0.010	
С	0.25		0.5	0.010		0.019	
c1			45 (	(typ.)			
D	4.8		5.0	0.188		0.196	
Е	5.8		6.2	0.228		0.244	
е		1.27			0.050		
e3		3.81			0.150		
F	3.8		4.0	0.14		0.157	
L	0.4		1.27	0.015		0.050	
М			0.6			0.023	

#### SO-8 MECHANICAL DATA



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